

Patent Abstracts of Japan

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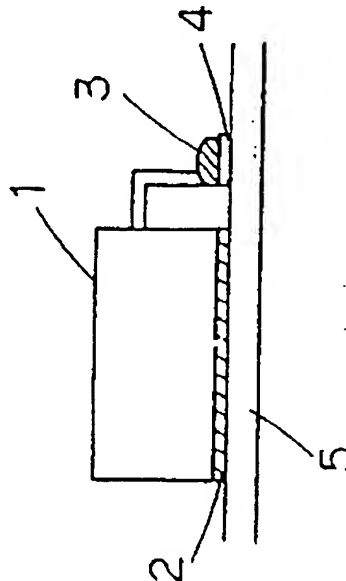
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APPLICANT : MURATA MFG CO LTD;

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TITLE : SURFACE MOUNTING TYPE
ELECTRONIC COMPONENT AND
MOUNTING METHOD THEREOF



ABSTRACT : PURPOSE: To improve stability in mounting a surface mount type electronic component on a board by coating at least part of the component with adhesive having properties to be softened at a high temperature, cured and dried at an ambient temperature.

CONSTITUTION: A surface mount type electronic component 1 in which its external connection part is pulled out only at one face of a component body is prepared. Then, the bottom of the body is coated with adhesive 2 having properties to be softened at a high temperature, cured and dried at an ambient temperature. Thereafter, the component 1 coated with the adhesive 2 is disposed on a board 5 coated with solder 3 on a conductive part 4. The board 5 on which the component 1 is disposed is heated to about 200°C by reflow solder, and the solder 3 and the adhesive 2 are melted. Subsequently, the melted solder 3 and adhesive 2 are cured at an ambient temperature, and the component 1 is fixed on the board 5.

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